



### **INA121**

# **FET-Input, Low Power INSTRUMENTATION AMPLIFIER**

### **FEATURES**

● LOW BIAS CURRENT: ±4pA

● LOW QUIESCENT CURRENT: ±450µA

● LOW INPUT OFFSET VOLTAGE: ±200µV

■ LOW INPUT OFFSET DRIFT: ±2µV/°C

LOW INPUT NOISE:  $20nV/\sqrt{Hz}$  at f = 1kHz (G =100)

HIGH CMR: 106dB

● WIDE SUPPLY RANGE: ±2.25V to ±18V

■ LOW NONLINEARITY ERROR: 0.001% max

INPUT PROTECTION TO ±40V

8-PIN DIP AND SO-8 SURFACE MOUNT

### **APPLICATIONS**

- LOW-LEVEL TRANSDUCER AMPLIFIERS Bridge, RTD, Thermocouple
- PHYSIOLOGICAL AMPLIFIERS ECG, EEG, EMG, Respiratory
- HIGH IMPEDANCE TRANSDUCERS
- CAPACITIVE SENSORS
- MULTI-CHANNEL DATA ACQUISITION
- PORTABLE, BATTERY OPERATED SYSTEMS
- GENERAL PURPOSE INSTRUMENTATION

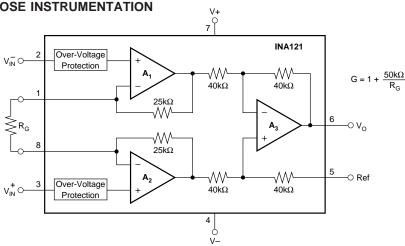
### DESCRIPTION

The INA121 is a FET-input, low power instrumentation amplifier offering excellent accuracy. Its versatile three-op amp design and very small size make it ideal for a variety of general purpose applications. Low bias current (±4pA) allows use with high impedance sources.

Gain can be set from 1V to 10,000V/V with a single external resistor. Internal input protection can withstand up to ±40V without damage.

The INA121 is laser-trimmed for very low offset voltage ( $\pm 200\mu V$ ), low offset drift ( $\pm 2\mu V/^{\circ}C$ ), and high common-mode rejection (106dB at G = 100). It operates on power supplies as low as  $\pm 2.25 \text{V}$  (+4.5V), allowing use in battery operated and single 5V systems. Quiescent current is only 450µA.

Package options include 8-pin plastic DIP and SO-8 surface mount. All are specified for the -40°C to +85°C industrial temperature range.



International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85706 • Tel: (520) 746-1111 • Twx: 910-952-1111 Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

# SPECIFICATIONS: $V_S = \pm 15V$

At  $T_A$  = +25°C,  $V_S$  = ±15V,  $R_L$  = 10k $\Omega$ , and IA reference = 0V, unless otherwise noted.

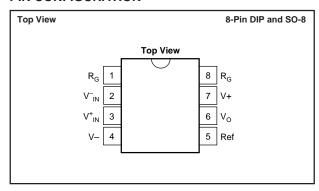
			INA121P, U					
PARAMETER	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT Offset Voltage, RTI vs Temperature vs Power Supply Long-Term Stability	$V_S = \pm 2.25 \text{V to } \pm 18 \text{V}$		±200±200/G ±2±2/G ±5±20/G ±0.5	±500±500/G ±5±20/G ±50±150/G		±300±200/G * * *	±1000±1000/G ±15±20/G *	μV μV/°C μV/V μV/mo
Impedance, Differential Common-Mode	V <sub>O</sub> = 0V		10 <sup>12</sup>    1 10 <sup>12</sup>    12			*		Ω    pF Ω    pF
Input Voltage Range Safe Input Voltage Common-Mode Rejection	\\ 12.5\\ to 12.5\\	See 1	Text and Typical	Curves ±40		*	*	V
Common-Mode Rejection	$V_{CM} = -12.5V \text{ to } 13.5V$ $G = 1$ $G = 10$ $G = 100$ $G = 1000$	78 91 96	86 100 106 106		72 85 90	* * * *		dB dB dB dB
BIAS CURRENT vs Temperature Offset Current vs Temperature	V <sub>CM</sub> = 0V		±4 See Typical Curv ±0.5 See Typical Curv			* * * *	*	pA pA
NOISE, RTI  Voltage Noise: f = 10Hz	$R_S = 0\Omega$ G = 100 G = 100 G = 100 G = 100		30 21 20 1			* * * *		nV/√Hz nV/√Hz nV/√Hz μVp-p fA/√Hz
<b>GAIN</b> Gain Equation Range of Gain Gain Error	$V_{O} = -14V \text{ to } 13.5V$ $G = 1$ $G = 10$ $G = 100$	1	1 + (50kΩ/R <sub>G</sub> ) ±0.01 ±0.03 ±0.05	10,000 ±0.05 ±0.4 ±0.5	*	* * * *	* ±0.1 ±0.5 ±0.7	V/V V/V % %
Gain vs Temperature <sup>(1)</sup>	G = 1000 G = 1 G > 1		±0.05 ±0.5 ±1 ±25	±10 ±100		* *	* *	% ppm/°C ppm/°C
Nonlinearity	$V_O = -14V \text{ to } 13.5V$ $G = 1$ $G = 10$ $G = 100$ $G = 1000$		±0.0002 ±0.0015 ±0.0015 ±0.002	±0.001 ±0.005 ±0.005		* * * *	±0.002 ±0.008 ±0.008	% of FSF % of FSF % of FSF % of FSF
OUTPUT Voltage: Positive Negative Positive Negative Capacitance Load Drive Short-Circuit Current	$R_L = 100k\Omega$ $R_L = 100k\Omega$ $R_L = 10k\Omega$ $R_L = 10k\Omega$	(V+)-1.5 (V-)+1	(V+)-0.9 (V-)+0.15 (V+)-0.9 (V-)+0.25 1000 ±14		*	* * * * * * *		V V V V pF mA
FREQUENCY RESPONSE Bandwidth, -3dB	G = 1 G = 10 G = 100 G = 1000		600 300 50 5			* * * *		kHz kHz kHz kHz
Slew Rate Settling Time, 0.01% Overload Recovery	$V_{O} = \pm 10V, G \le 10$ G = 1  to  10 G = 100 G = 1000 50% Input Overload		0.7 20 35 260 5			* * * * *		V/μs μs μs μs μs
POWER SUPPLY Voltage Range Quiescent Current	I <sub>O</sub> = 0V	±2.25	±15 ±450	±18 ±525	*	*	*	V μA
TEMPERATURE RANGE Specification Operating Storage Thermal Resistance, $\theta_{IA}$		-40 -55 -55		85 125 125	* * *		* * *	ပဲ လို လို
8-Lead DIP SO-8 Surface Mount			100 150			*		°C/W

<sup>\*</sup> Specification same as INA121P, U.

NOTE: (1) Temperature coefficient of the "Internal Resistor" in the gain equation. Does not include TCR of gain-setting resistor, R<sub>G</sub>.



#### PIN CONFIGURATION



# ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage	
Analog Input Voltage Range  Output Short-Circuit (to ground)	
Operating Temperature	–55°C to +125°C
Storage Temperature	
Junction Temperature Lead Temperature (soldering, 10s)	

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability.

#### PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER(1)	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER(2)	TRANSPORT MEDIA
Single						
INA121P	8-Pin DIP	006	-40°C to +85°C	INA121P	INA121P	Rails
INA121PA	8-Pin DIP	006	-40°C to +85°C	INA121PA	INA121PA	Rails
INA121U	SO-8 Surface-Mount	182	-40°C to +85°C	INA121U	INA121U	Rails
"	"	"	"	"	INA121U/2K5	Tape and Reel
INA121UA	SO-8 Surface-Mount	182	-40°C to +85°C	INA121UA	INA121UA	Rails
н	"	"	n	п	INA121UA/2K5	Tape and Reel

NOTES: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book. (2) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /2K5 indicates 2500 devices per reel). Ordering 2500 pieces of "INA121U/2K5" will get a single 2500-piece Tape and Reel. For detailed Tape and Reel mechanical information, refer to Appendix B of Burr-Brown IC Data Book.

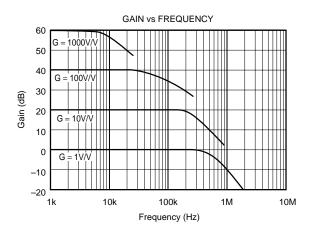
The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.

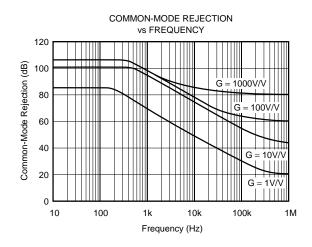
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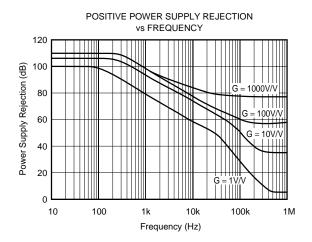
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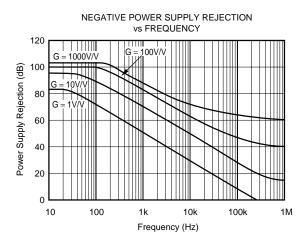
### **TYPICAL PERFORMANCE CURVES**

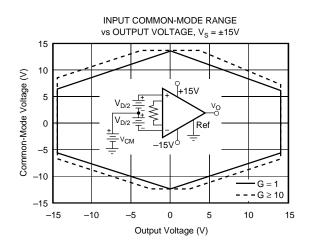
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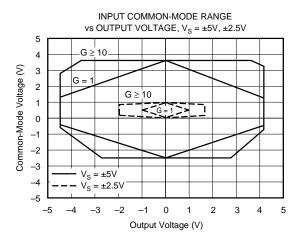








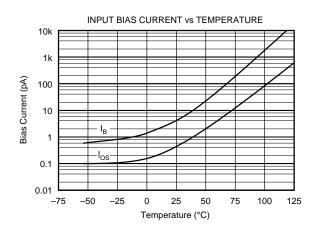


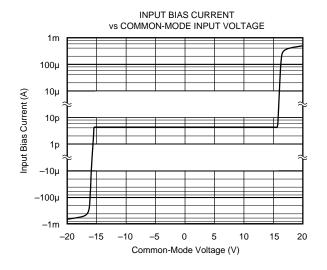


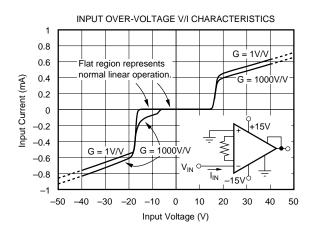


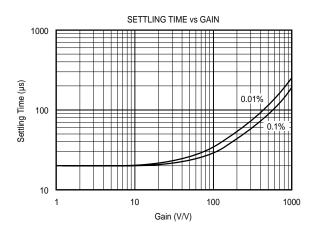
### **TYPICAL PERFORMANCE CURVES (CONT)**

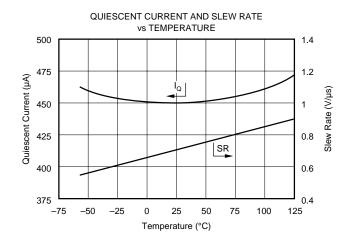
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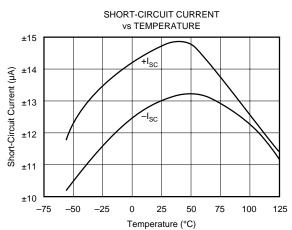






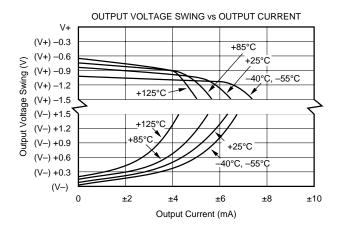


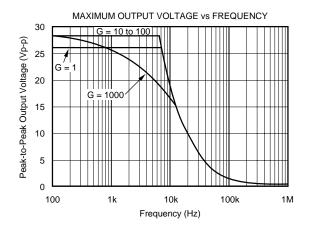


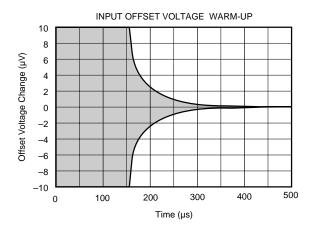


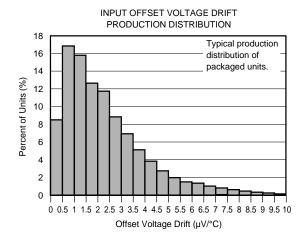
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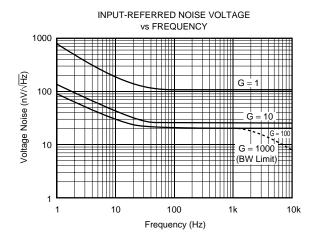
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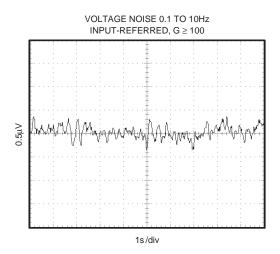








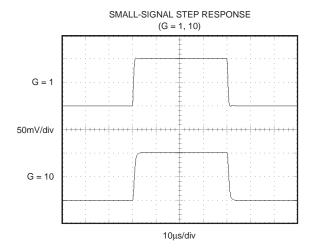


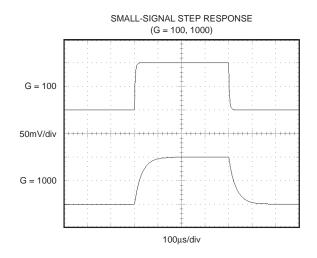


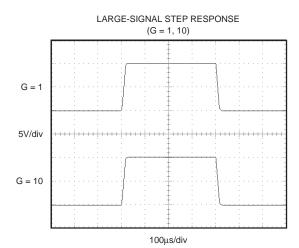


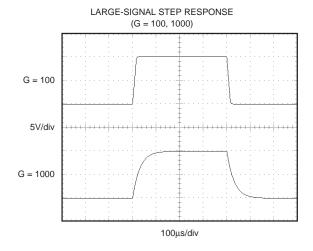
## TYPICAL PERFORMANCE CURVES (CONT)

At  $T_A$  = +25°C,  $V_S$  = ±15V, unless otherwise noted.









### APPLICATION INFORMATION

Figure 1 shows the basic connections required for operation of the INA121. Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output reference (Ref) terminal which is normally grounded. This must be a low-impedance connection to assure good common-mode rejection. A resistance of  $8\Omega$  in series with the Ref pin will cause a typical device to degrade to approximately 80dB CMR (G=1).

#### **SETTING THE GAIN**

Gain of the INA121 is set by connecting a single external resistor,  $R_G$ , connected between pins 1 and 8:

$$G = 1 + \frac{50k\Omega}{R_G} \tag{1}$$

Commonly used gains and resistor values are shown in Figure 1.

The  $50k\Omega$  term in Equation 1 comes from the sum of the two internal feedback resistors of  $A_1$  and  $A_2$ . These on-chip metal film resistors are laser trimmed to accurate absolute values. The accuracy and temperature coefficient of these resistors are included in the gain accuracy and drift specifications of the INA121.

The stability and temperature drift of the external gain setting resistor,  $R_G$ , also affects gain.  $R_G$ 's contribution to gain accuracy and drift can be directly inferred from the gain equation (1). Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance which will contribute additional gain error (possibly an unstable gain error) in gains of approximately 100 or greater.

#### **DYNAMIC PERFORMANCE**

The typical performance curve "Gain vs Frequency" shows that, despite its low quiescent current, the INA121 achieves wide bandwidth, even at high gain. This is due to the current-feedback topology of the INA121. Settling time also remains excellent at high gain.

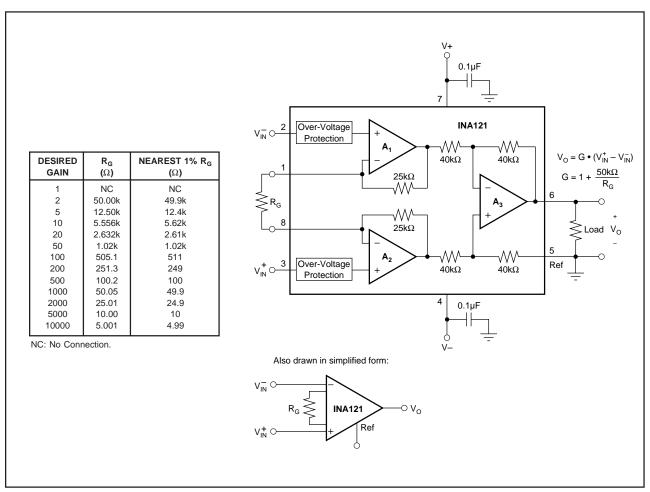


FIGURE 1. Basic Connections.



The INA121 provides excellent rejection of high frequency common-mode signals. The typical performance curve, "Common-Mode Rejection vs Frequency" shows this behavior. If the inputs are not properly balanced, however, common-mode signals can be converted to differential signals. Run the  $V_{\rm IN}^+$  and  $V_{\rm IN}^-$  connections directly adjacent each other, from the source signal all the way to the input pins. If possible use a ground plane under both input traces. Avoid running other potentially noisy lines near the inputs.

#### NOISE AND ACCURACY PERFORMANCE

The INA121's FET input circuitry provides low input bias current and high speed. It achieves lower noise and higher accuracy with high impedance sources. With source impedances of  $2k\Omega$  to  $50k\Omega$  the INA114, INA128, or INA129 may provide lower offset voltage and drift. For very low source impedance ( $\leq 1k\Omega$ ), the INA103 may provide improved accuracy and lower noise. At very high source impedances ( $> 1M\Omega$ ) the INA116 is recommended.

#### **OFFSET TRIMMING**

The INA121 is laser trimmed for low offset voltage and drift. Most applications require no external offset adjustment. Figure 2 shows an optional circuit for trimming the output offset voltage. The voltage applied to Ref terminal is summed at the output. The op amp buffer provides low impedance at the Ref terminal to preserve good common-mode rejection. Trim circuits with higher source impedance should be buffered with an op amp follower circuit to assure low impedance on the Ref pin.

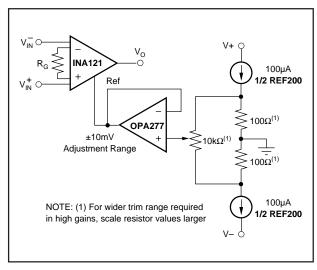


FIGURE 2. Optional Trimming of Output Offset Voltage.

#### INPUT BIAS CURRENT RETURN PATH

The input impedance of the INA121 is extremely high—approximately  $10^{12}\Omega$ . However, a path must be provided for the input bias current of both inputs. This input bias current is typically 4pA. High input impedance means that this input bias current changes very little with varying input voltage.

Input circuitry must provide a path for this input bias current if the INA121 is to operate properly. Figure 3 shows various provisions for an input bias current path. Without a bias current return path, the inputs will float to a potential which exceeds the common-mode range of the INA121 and the input amplifiers will saturate.

If the differential source resistance is low, the bias current return path can be connected to one input (see the thermocouple example in Figure 3). With higher source impedance, using two resistors provides a balanced input with possible advantages of lower input offset voltage due to bias current and better high-frequency common-mode rejection.

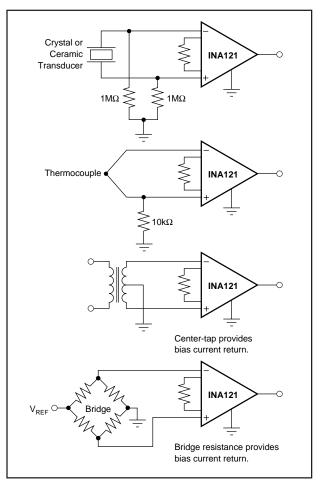


FIGURE 3. Providing an Input Common-Mode Current Path.

#### INPUT COMMON-MODE RANGE

The linear input voltage range of the input circuitry of the INA121 is from approximately 1.2V below the positive supply voltage to 2.1V above the negative supply. A differential input voltage causes the output voltage to increase. The linear input range, however, will be limited by the output voltage swing of amplifiers  $A_1$  and  $A_2$ . So the linear common-mode input range is related to the output voltage of the complete amplifier. This behavior also depends on supply voltage—see typical performance curve "Input Common-Mode Range vs Output Voltage".



A combination of common-mode and differential input voltage can cause the output of  $A_1$  or  $A_2$  to saturate. Figure 4 shows the output voltage swing of  $A_1$  and  $A_2$  expressed in terms of a common-mode and differential input voltages. For applications where input common-mode range must be maximized, limit the output voltage swing by connecting the INA121 in a lower gain (see performance curve "Input Common-Mode Voltage Range vs Output Voltage"). If necessary, add gain after the INA121 to increase the voltage swing.

Input-overload can produce an output voltage that appears normal. For example, if an input overload condition drives both input amplifiers to their positive output swing limit, the difference voltage measured by the output amplifier will be near zero. The output of  $A_3$  will be near 0V even though both inputs are overloaded.

#### LOW VOLTAGE OPERATION

The INA121 can be operated on power supplies as low as  $\pm 2.25$ V. Performance remains excellent with power supplies ranging from  $\pm 2.25$ V to  $\pm 18$ V. Most parameters vary only slightly throughout this supply voltage range—see typical

performance curves. Operation at very low supply voltage requires careful attention to assure that the input voltages remain within their linear range. Voltage swing requirements of internal nodes limit the input common-mode range with low power supply voltage. Typical performance curves, "Input Common-Mode Range vs Output Voltage" show the range of linear operation for  $\pm 15$ V,  $\pm 5$ V, and  $\pm 2.5$ V supplies.

#### **INPUT FILTERING**

The INA121's FET input allows use of an R/C input filter without creating large offsets due to input bias current. Figure 5 shows proper implementation of this input filter to preserve the INA121's excellent high frequency commonmode rejection. Mismatch of the common-mode input time constant ( $R_1C_1$  and  $R_2C_2$ ), either from stray capacitance or mismatched values, causes a high frequency common-mode signal to be converted to a differential signal. This degrades common-mode rejection. The differential input capacitor,  $C_3$ , reduces the bandwidth and mitigates the effects of mismatch in  $C_1$  and  $C_2$ . Make  $C_3$  much larger than  $C_1$  and  $C_2$ . If properly matched,  $C_1$  and  $C_2$  also improve ac CMR.

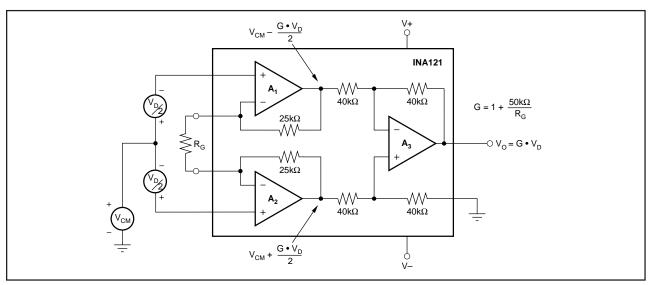


FIGURE 4. Voltage Swing of A<sub>1</sub> and A<sub>2</sub>.

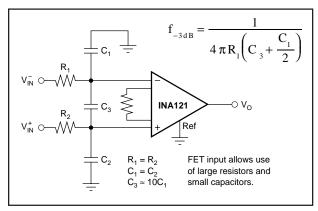


FIGURE 5. Input Low-Pass Filter.

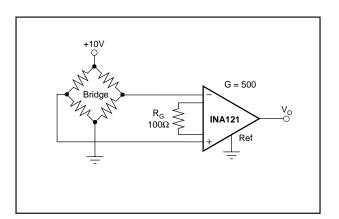


FIGURE 6. Bridge Transducer Amplifier.



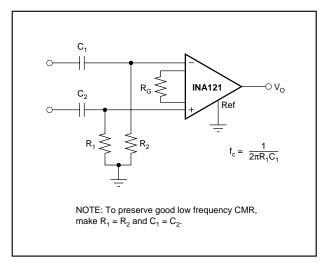


FIGURE 7. High-Pass Input Filter.

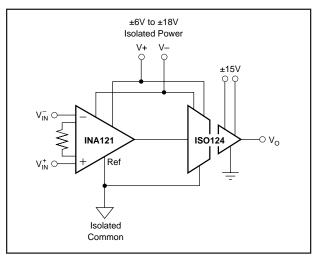


FIGURE 8. Galvanically Isolated Instrumentation Amplifier.

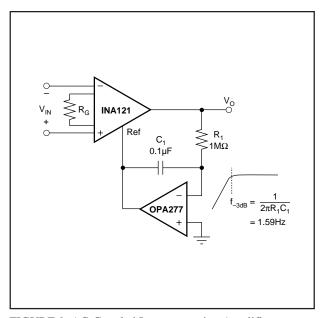


FIGURE 9. AC-Coupled Instrumentation Amplifier.

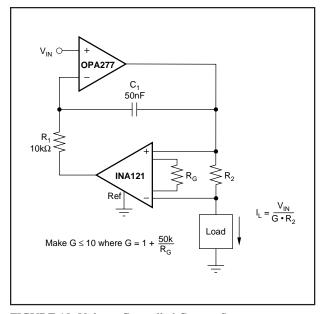


FIGURE 10. Voltage Controlled Current Source.

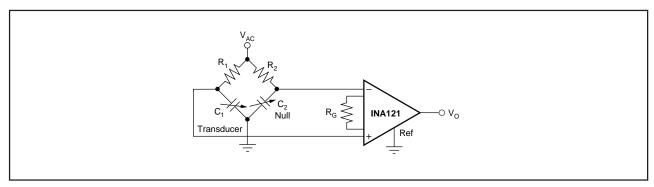


FIGURE 11. Capacitive Bridge Transducer Circuit.

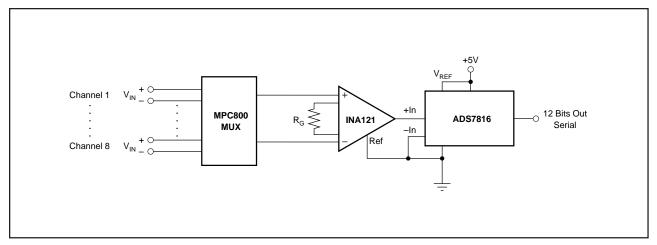


FIGURE 12. Multiplexed-Input Data Acquisition System.

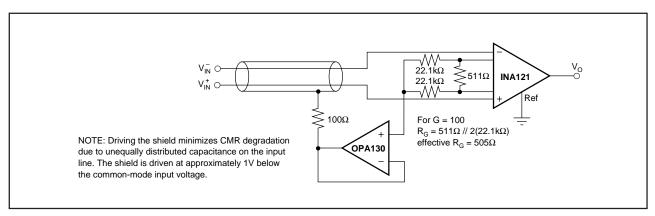


FIGURE 13. Shield Driver Circuit.

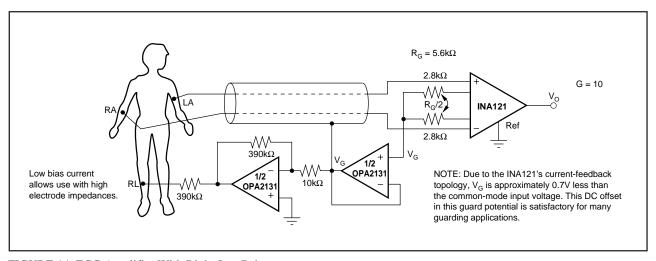


FIGURE 14. ECG Amplifier With Right-Leg Drive.





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#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
INA121P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	INA121P A	Samples
INA121PA	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA121P A	Samples
INA121PAG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type		INA121P A	Samples
INA121PG4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	INA121P A	Sample
INA121U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U	Sample
INA121U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U	Sample
INA121U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U	Sample
INA121UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U A	Sample
INA121UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U A	Sample
INA121UA/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U A	Sample
INA121UAE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U A	Sample
INA121UG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		INA 121U	Sample

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE**: TI has discontinued the production of the device.



### **PACKAGE OPTION ADDENDUM**

11-Jul-2013

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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### PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA121U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
INA121UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA121U/2K5	SOIC	D	8	2500	367.0	367.0	35.0
INA121UA/2K5	SOIC	D	8	2500	367.0	367.0	35.0

### P (R-PDIP-T8)

### PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



### D (R-PDSO-G8)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



# D (R-PDSO-G8)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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